

High Voltage Standard Rectifier

$$V_{RRM} = 2200\text{ V}$$

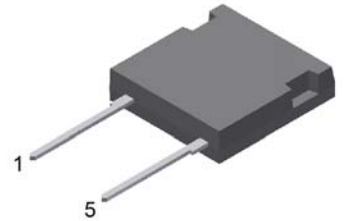
$$I_{FAV} = 30\text{ A}$$

$$V_F = 1,22\text{ V}$$

Single Diode

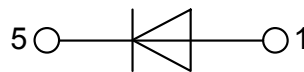
Part number

DNA30E2200FE



Backside: isolated

 E72873



Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very low forward voltage drop
- Improved thermal behaviour

Applications:

- Diode for main rectification
- For single and three phase bridge configurations

Package: i4-Pac

- Isolation Voltage: 3000 V~
- Industry convenient outline
- RoHS compliant
- Epoxy meets UL 94V-0
- Soldering pins for PCB mounting
- Backside: DCB ceramic
- Reduced weight
- Advanced power cycling

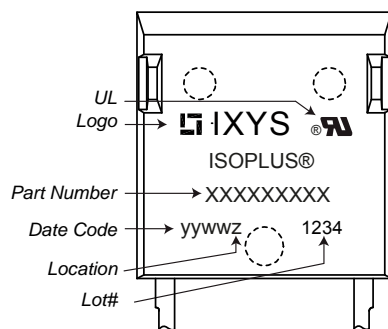
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Rectifier				Ratings			
Symbol	Definition	Conditions		min.	typ.	max.	Unit
V_{RSM}	max. non-repetitive reverse blocking voltage					2300	V
V_{RRM}	max. repetitive reverse blocking voltage					2200	V
I_R	reverse current	$V_R = 2200$ V	$T_{VJ} = 25^\circ\text{C}$			40	μA
		$V_R = 2200$ V	$T_{VJ} = 150^\circ\text{C}$			1,5	mA
V_F	forward voltage drop	$I_F = 30$ A	$T_{VJ} = 25^\circ\text{C}$			1,25	V
						1,50	V
		$I_F = 60$ A	$T_{VJ} = 150^\circ\text{C}$			1,22	V
						1,59	V
I_{FAV}	average forward current	$T_C = 110^\circ\text{C}$ rectangular	$T_{VJ} = 175^\circ\text{C}$			30	A
V_{FO}	threshold voltage	} for power loss calculation only				0,83	V
r_F	slope resistance					12,8	m Ω
R_{thJC}	thermal resistance junction to case					1,35	K/W
R_{thCH}	thermal resistance case to heatsink				0,2		K/W
P_{tot}	total power dissipation			$T_C = 25^\circ\text{C}$		110	W
I_{FSM}	max. forward surge current	$t = 10$ ms; (50 Hz), sine	$T_{VJ} = 45^\circ\text{C}$			370	A
		$t = 8,3$ ms; (60 Hz), sine	$V_R = 0$ V			400	A
		$t = 10$ ms; (50 Hz), sine	$T_{VJ} = 150^\circ\text{C}$			315	A
		$t = 8,3$ ms; (60 Hz), sine	$V_R = 0$ V			340	A
I^2t	value for fusing	$t = 10$ ms; (50 Hz), sine	$T_{VJ} = 45^\circ\text{C}$			685	A ² s
		$t = 8,3$ ms; (60 Hz), sine	$V_R = 0$ V			665	A ² s
		$t = 10$ ms; (50 Hz), sine	$T_{VJ} = 150^\circ\text{C}$			495	A ² s
		$t = 8,3$ ms; (60 Hz), sine	$V_R = 0$ V			480	A ² s
C_J	junction capacitance	$V_R = 700$ V; $f = 1$ MHz	$T_{VJ} = 25^\circ\text{C}$		7		pF

Package i4-Pac			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
I_{RMS}	RMS current	per terminal			70	A
T_{VJ}	virtual junction temperature		-55		175	°C
T_{op}	operation temperature		-55		150	°C
T_{stg}	storage temperature		-55		150	°C
Weight				5,5		g
F_C	mounting force with clip		20		120	N
$d_{Spp/App}$	creepage distance on surface striking distance through air	terminal to terminal	13,8			mm
$d_{Spb/Apb}$		terminal to backside	5,1			mm
V_{ISOL}	isolation voltage	t = 1 second t = 1 minute 50/60 Hz, RMS; $I_{ISOL} \leq 1$ mA	3000			V
			2500			V

Product Marking



Part description

D = Diode
 N = High Voltage Standard Rectifier
 A = ($\geq 2000V$)
 30 = Current Rating [A]
 E = Single Diode
 2200 = Reverse Voltage [V]
 FE = i4-Pac (2HV)

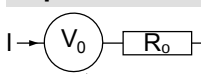
Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DNA30E2200FE	DNA30E2200FE	Tube	25	508861

Similar Part	Package	Voltage class
DNA30E2200PA	TO-220AC	2200
DNA30E2200PZ	TO-263AB (D2Pak) (2HV)	2200
DNA30EM2200PZ	TO-263AB (D2Pak) (2HV)	2200
DNA30E2200IY	TO-262 (2HV) (I2PAK)	2200

Equivalent Circuits for Simulation

* on die level

$T_{VJ} = 175^\circ C$

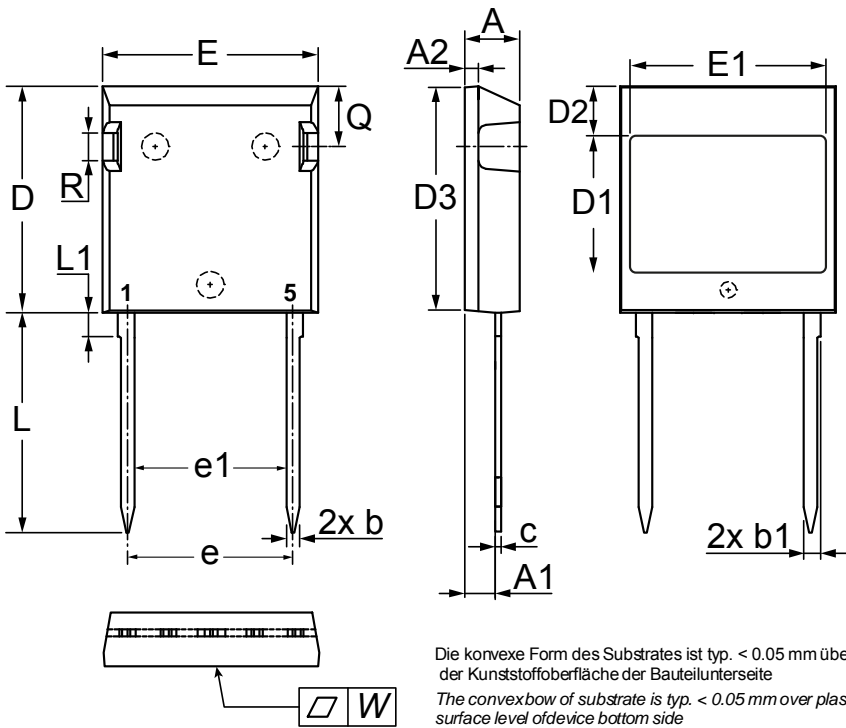


Rectifier

$V_{0\ max}$	threshold voltage	0,83	V
$R_{0\ max}$	slope resistance *	10,2	mΩ

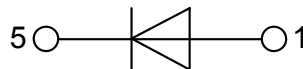


Outlines i4-Pac



Die konvexe Form des Substrates ist typ. < 0.05 mm über der Kunststoffoberfläche der Bauteilunterseite
The convexbow of substrate is typ. < 0.05 mm over plastic surface level of device bottom side

Dim.	Millimeter		Inches	
	min	max	min	max
A	4.83	5.21	0.190	0.205
A1	2.59	3.00	0.102	0.118
A2	1.17	2.16	0.046	0.085
b	1.14	1.40	0.045	0.055
b1	1.47	1.73	0.058	0.068
c	0.51	0.74	0.020	0.029
D	20.80	21.34	0.819	0.840
D1	11.70	12.30	0.460	0.484
D2	5.50	6.10	0.216	0.240
D3	20.30	20.70	0.799	0.815
E	19.56	20.29	0.770	0.799
E1	17.50	18.10	0.689	0.712
e	15.24	BSC	0.600	BSC
e1	14.10	BSC	0.555	BSC
L	19.81	21.34	0.780	0.840
L1	2.11	2.59	0.083	0.102
Q	5.33	6.20	0.210	0.244
R	2.54	4.57	0.100	0.180
W	-	0.10	-	0.004



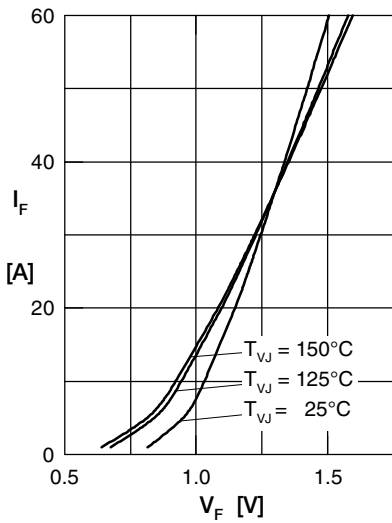
Rectifier


Fig. 1 Forward current versus voltage drop per diode

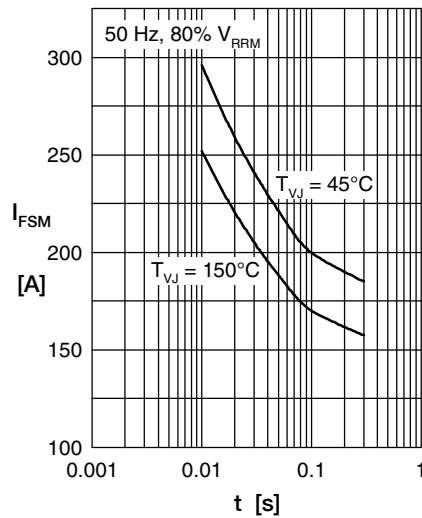


Fig. 2 Surge overload current

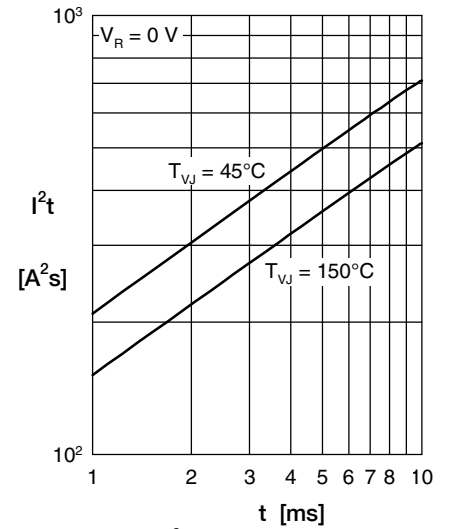
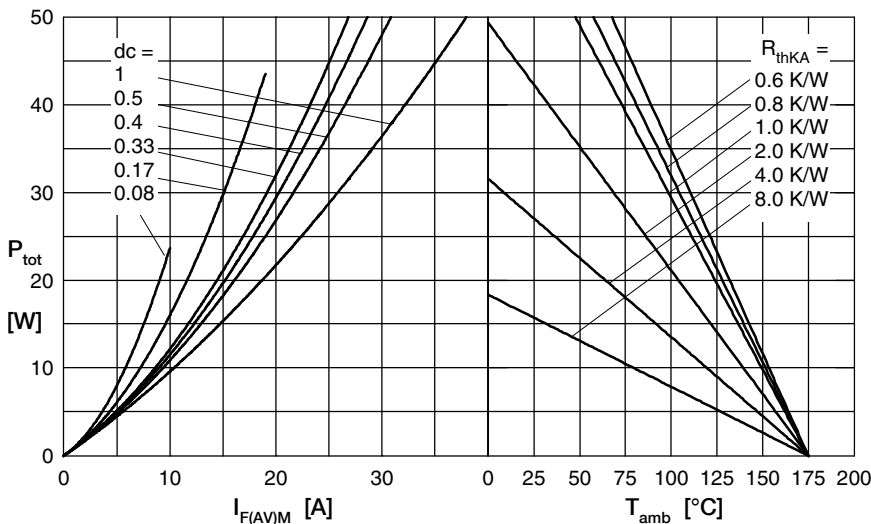

 Fig. 3 I^2t versus time per diode


Fig. 4 Power dissipation versus direct output current & ambient temperature

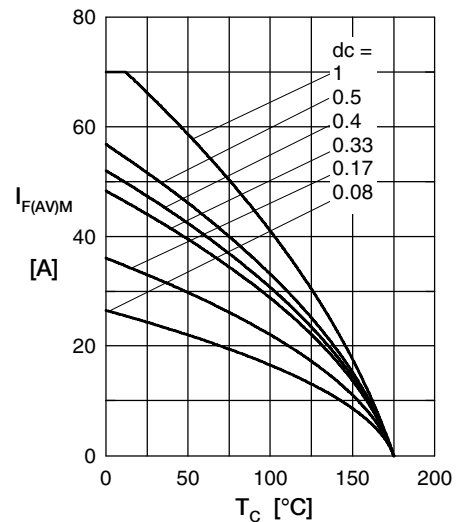


Fig. 5 Max. forward current versus case temperature

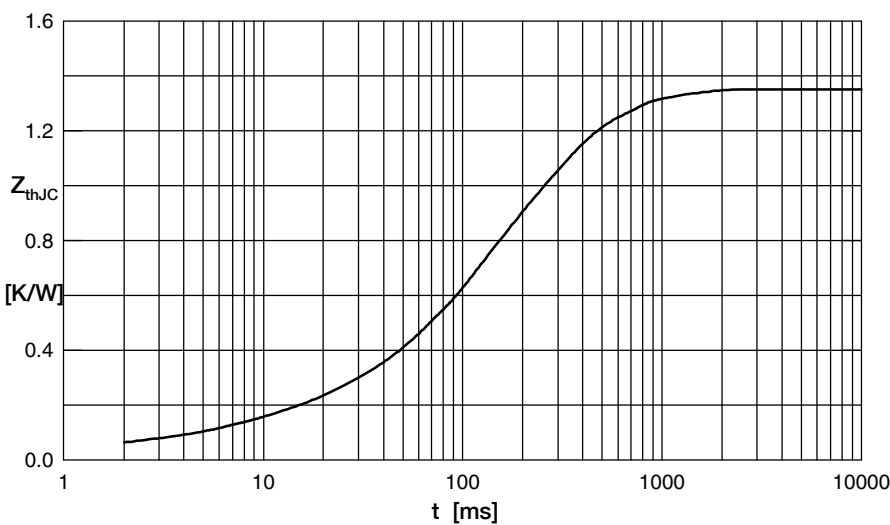


Fig. 6 Transient thermal impedance junction to case

 Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.03	0.0003
2	0.072	0.0065
3	0.122	0.083
4	0.736	0.152
5	0.39	0.4